

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-29. (Canceled).

30. (Currently Amended) An apparatus for electrodeposited film formation comprising:

an electrolyte solution bath holding: (a) an electrolyte solution containing ions to constitute an electrodeposited film and (b) an object to be treated of which at least the surface permits generation of charged particles when irradiated with a laser beam and onto which the electrodeposited film is to be deposited; and

a mode-locked laser whose pulse width is less than a picosecond and which irradiates at least part of the object to be treated positioned in the electrolyte solution to thereby ~~excite~~ generate hot electrons in the laser-irradiated part and form the electrodeposited film at the laser-irradiated part.

31. (Original) An apparatus for electrodeposited film formation, according to Claim 30, further provided with:

an opposite electrode held separated from the object to be treated in the electrolyte solution; and

a power source for applying a bias voltage between the object to be treated and the opposite electrode.

32. (Previously Presented) The apparatus according to Claim 30, wherein said electrolyte solution contains at least one plating metal selected from the group consisting of Cu, Pt, Zn, Ni, Cd, Cr, Sn, Au, Ag, Rh, Ru, Pb, Ti, Pd, Co, B, Ge, Al, In, Ir, Mo, W, V and Ta.

33. (Previously Presented) The apparatus according to Claim 32, wherein said electrolyte solution contains at least one of Cu, Pt, Zn or Ni.

34. (Previously Presented) The apparatus according to Claim 30, wherein the object to be treated comprises a metal selected from the group consisting of Au, Cu, Pt, Zn, Cd, CrSnAu, AgRh, Ru, Pb, TiPd, Co, B, Ge, Al, In, Ir, Mo, W, V, Ta, Ni, Sn and alloys thereof.

35. (Previously Presented) The apparatus according to Claim 30, wherein the object to be treated comprises at least one of Au, Cu, Pt or Zn.

36. (Previously Presented) The apparatus according to Claim 30, wherein said electrolyte solution is an aqueous solution.

37. (Previously Presented) The apparatus according to Claim 36, wherein said aqueous solution contains 2 to 18% by weight plating metal.

38. (Previously Presented) The apparatus according to claim 30, wherein said mode-locked laser is a mode-locked titanium sapphire laser.

39. (Currently Amended) An apparatus for electrodeposited film formation comprising:

an electrolyte solution bath holding: (a) an electrolyte solution containing ions to constitute an electrodeposited film and (b) an object to be treated of which at least the surface permits generation of charged particles when irradiated with a laser beam and onto which the electrodeposited film is to be deposited; and

a pulse laser with an electric field in the order of tens of GW/cm^2 and whose pulse width is less than a picosecond and which irradiates at least part of the object to be treated positioned in the electrolyte solution to thereby ~~excite~~ generate hot electrons in the laser-irradiated part and form the electrodeposited film at the laser-irradiated part.

40. (Previously Presented) An apparatus for electrodeposited film formation, according to Claim 39, further provided with:

an opposite electrode held separated from the object to be treated in the electrolyte solution; and

a power source for applying a bias voltage between the object to be treated and the opposite electrode.

41. (Previously Presented) The apparatus according to Claim 39, wherein said electrolyte solution contains at least one plating metal selected from the group consisting of Cu, Pt, Zn, Ni, Cd, Cr, Sn, Au, Ag, Rh, Ru, Pb, Ti, Pd, Co, B, Ge, Al, In, Ir, Mo, W, V and Ta.

42. (Previously Presented) The apparatus according to Claim 41, wherein said electrolyte solution contains at least one of Cu, Pt, Zn or Ni.

43. (Previously Presented) The apparatus according to Claim 39, wherein the object to be treated comprises a metal selected from the group consisting of Au, Cu, Pt, Zn, Cd, CrSnAu, AgRh, Ru, Pb, TiPd, Co, B, Ge, Al, In, Ir, Mo, W, V, Ta, Ni, Sn and alloys thereof.

44. (Previously Presented) The apparatus according to Claim 39, wherein the object to be treated comprises at least one of Au, Cu, Pt or Zn.

45. (Previously Presented) The apparatus according to Claim 39, wherein said electrolyte solution is an aqueous solution.

46. (Previously Presented) The apparatus according to Claim 45, wherein said aqueous solution contains 2 to 18% by weight plating metal.